



Layer Stacking  
 TOP  
 BOTTOM

Overall Board Thickness: 62 Mil  
 Soldermask Color: RED  
 Silkscreen Color: White  
 Drill hole tolerance: +/-3 Mil

1		TOP COMPONENT	
COMPANY	TI-SVA		
PCB PART NUMBER	MCU	REV	1
DATE	2/14/15		
NOTES			

SIZE	QTY	SYM	PLATED	TOL
122	4	✕	NO	+/-0.0
13	93	□	YES	+/-0.0
47.24	4	◇	NO	+/-0.0
35.04	32	⊗	NO	+/-0.0
25	5	⊗	YES	+/-0.0
19.69 x 47.24	2	⊕	YES	+/-0.0

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